

Product Change Notice (PCN)

Subject: Data Sheet & Wafer Fabrication Site Change for Listed Intersil X28HC256* Products Publication Date: 4/1/2015 Effective Date: 7/29/2015

Revision Description: Initial Release

Description of Change:

Data Sheet and Wafer Fabrication Site Change for Listed Intersil X28HC256* Products

Reason for Change:

This notice is to inform you that Intersil has qualified Intersil's Palm Bay, Florida facility for wafer fabrication of the listed C5 technology products. The process technology qualification activity is complete. The data sheet has been updated to align the specification with the characteristics of the product (silicon) fabricated in the Intersil fabrication facility. The only change to the datasheet is reducing the endurance write cycles from 1,000,000 to 100,000 cycles. The updated data sheet is available on the Intersil web site at x28hc256 Datasheet. As of this notice, the data sheet updates and process qualification activities are complete. Product validation is in progress and expected to complete by July 29, 2015.

Impact on fit, form, function, quality & reliability:

The product and site qualification plans are designed using JEDEC and other applicable standards to confirm there is not impact to form, fit, function, or interchangeability of the product except as outlined in this PCN. A summary of the qualification plan is included for reference. The qualification results will be available for review upon completion by request. The remainder of the manufacturing operations (package assembly, package electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems. The ICP Test Report for the Palm Bay fabrication facility is located on Intersil's Environmental web site under Material Sub-Group: "Silicon"; Material "die" and the PDF file is titled Intersil Corporation. http://www.intersil.com/en/support/environmental.html#WA;

Product Identification:

Product affected by this change is identifiable via Intersil's internal traceability system.

Qualification status: In progress, see attached Sample availability: 7/29/2015 Device material declaration: Available upon request

Questions or requests pertaining to this change notice, including additional data or samples, must be sent to Intersil within 30 days of the publication date.

 For additional information regarding this notice, please contact your regional change coordinator (below)

 Americas: PCN-US@INTERSIL.COM
 Europe: PCN-EU@INTERSIL.COM
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Appendix A

X28HC256J-12	X28HC256JI-90R5420	X28HC256JZ-15	X28HC256S-90
X28HC256J-12T1	X28HC256JI-90T1	X28HC256JZ-15T1	X28HC256SI-12
X28HC256J-15	X28HC256JI-90T1C7992	X28HC256JZ-90	X28HC256SI-15
X28HC256J-15T1	X28HC256JIZ-12	X28HC256JZ-90T1	X28HC256SI-15T1
X28HC256JI-12	X28HC256JIZ-12T1	X28HC256PIZ-12	X28HC256SI-90
X28HC256JI-12T1	X28HC256JIZ-15	X28HC256PIZ-15	X28HC256SIZ-12
X28HC256JI-15	X28HC256JIZ-15T1	X28HC256PIZ-90	X28HC256SIZ-15
X28HC256JI-15T1	X28HC256JIZ-90	X28HC256PZ-12	X28HC256SIZ-90
X28HC256JI-15T2	X28HC256JIZ-90T1	X28HC256PZ-15	X28HC256SZ-12
X28HC256JI-90	X28HC256JZ-12	X28HC256PZ-90	X28HC256W
X28HC256JI-90C7992	X28HC256JZ-12T1	X28HC256S-12	X28HC256WC6721

Appendix B

Stress / Conditions	Duration	X5043S8IZ2.7AT1	X9C103SIZT1	X28HC64J-12	X28HC256J-12
High Temp Operating Life +125°C	1000 Hours	N = 234 Acc = 0	N = 156 Acc = 0	N/A	N/A
Moisture Sensitivity Classification		N = 44 Acc = 0 L1 PBFREE	N = 44 Acc = 0 L1 PBFREE	N = 44 Acc = 0 L1 PBFREE	N = 44 Acc = 0 L3 PBFREE
Unbiased HAST +130C / 85% RH	96 Hrs	N = 78 Acc = 0			
Temp Cycle +150C / -65C	500 Cy	N = 78 Acc = 0			
Biased HAST +130C / 85% RH	96 Hrs	N = 78 Acc = 0	N = 78 Acc = 0	N = 156 Acc = 0	N = 156 Acc = 0
High Temperature Storage T _A = +150C	1000 Hrs	N = 78 Acc = 0			
EEPROM Endurance 100000 cycles	100k cycles	Note 1	Note 1	N/A	N/A
EEPROM Retention T _A = +150C	1000 Hrs	Note 1	Note 1	N/A	N/A

Note 1: Endurance & Retention to meet or exceed current fab control

Qualification by Extension

Qualification Completed/Passed